

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	182	264/610.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/12/01 17:16
L2	289	264/628.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/12/01 17:16
L3	944	capillary.clm. and bonding.clm.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/12/01 17:16
L4	453	capillary.clm. and bonding.clm. and semiconductor	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/12/01 17:16
L5	222	capillary.clm. and bonding.clm. and semiconductor.clm.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/12/01 17:16
L6	76	capillary.clm. and bonding.clm. and semiconductor.clm. and tool	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/12/01 17:16
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L9	603	ceramic.clm. and capillary.clm.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/12/01 17:16
L10	192	ceramic.clm. and capillary.clm. and bonding	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/12/01 17:16
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L12	603	ceramic.clm. and capillary.clm.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/12/01 17:16
L13	34	ceramic.clm. and capillary.clm. and "264"/\$8.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/12/01 17:16
L14	192	ceramic.clm. and capillary.clm. and bonding	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/12/01 17:16
L15	61	ceramic.clm. and capillary.clm. and bonding.clm.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/12/01 17:16
L16	54	ceramic.clm. and capillary.clm. and bonding.clm. and process	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/12/01 17:16

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L20	18	ceramic.clm. and capillary.clm. and bonding.clm. and (binder or thermoplastic)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/12/01 17:16
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L22	453	capillary.clm. and bonding.clm. and semiconductor	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/12/01 17:16

L23	222	capillary.clm. and bonding.clm. and semiconductor.clm.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/12/01 17:16
L24	944	L21 or L22 or L23	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/12/01 17:16
L25	76	capillary.clm. and bonding.clm. and semiconductor.clm. and tool	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/12/01 17:16
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L28	603	ceramic.clm. and capillary.clm.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/12/01 17:16
L29	192	ceramic.clm. and capillary.clm. and bonding	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/12/01 17:16
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L33	192	ceramic.clm. and capillary.clm. and bonding	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/12/01 17:16
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L37	18	ceramic.clm. and capillary.clm. and bonding.clm. and (binder or thermoplastic)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/12/01 17:16
L38	316	264/669.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/12/01 17:16
L39	250	264/670.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/12/01 17:16

L40	303	264/614.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/12/01 17:16
L41	106	264/629.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/12/01 17:16
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L46	0	65/31.11.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/12/01 17:16
L47	852	65/111.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/12/01 17:16

L48	7	65/111.ccls. and color.clm.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/12/01 17:16
L49	113	65/111.ccls. and color	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/12/01 17:16
L50	165	photolithography and blanks and cutting	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/12/01 17:16
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L53	73	"5217154"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/12/01 17:16
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L63	453	capillary.clm. and bonding.clm. and semiconductor	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/12/01 17:16

L64	222	capillary.clm. and bonding.clm. and semiconductor.clm.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/12/01 17:16
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L67	603	ceramic.clm. and capillary.clm.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/12/01 17:16
L68	192	ceramic.clm. and capillary.clm. and bonding	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/12/01 17:16
L69	603	ceramic.clm. and capillary.clm.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/12/01 17:16
L70	192	ceramic.clm. and capillary.clm. and bonding	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/12/01 17:16
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L72	54	ceramic.clm. and capillary.clm. and bonding.clm. and process	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR .	OFF	2005/12/01 17:16
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L75	944	capillary.clm. and bonding.clm.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/12/01 17:16
L76	453	capillary.clm. and bonding.clm. and semiconductor	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/12/01 17:16
L77	222	capillary.clm. and bonding.clm. and semiconductor.clm.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/12/01 17:16
L78	944	L75 or L76 or L77	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/12/01 17:16
L79	76	capillary.clm. and bonding.clm. and semiconductor.clm. and tool	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/12/01 17:16
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L83	192	ceramic.clm. and capillary.clm. and bonding	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/12/01 17:16
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L92	316	264/669.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/12/01 17:16
L93	250	264/670.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/12/01 17:16
L94	303	264/614.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/12/01 17:16
L95	106	264/629.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/12/01 17:16
L96	1428	228/4.5.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/12/01 17:16
L97	0	65/31.1.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/12/01 17:16

L98	0	65/31.11.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/12/01 17:16
L99	852	65/111.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/12/01 17:16
L100	76	capillary.clm. and bonding.clm. and semiconductor.clm. and tool	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/12/01 17:16
L101	61	ceramic.clm. and capillary.clm. and bonding.clm.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/12/01 17:16
L102	34	ceramic.clm. and capillary.clm. and "264"/\$8.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/12/01 17:16
L103	49	("2892924" "3538205" "3660050" "3986653" "4020543" "4171477" "4182947" "4315128" "4331048" "4387283" "4390771" "4502983" "4513190" "4691854" "4705204" "4897710" "4909427" "4998002" "5178742" "5180093" "5214259" "5217154" "5280979" "5290507" "5367956" "5463197" "5463896" "5491605" "5527441" "5544804" "5601740" "5616257" "5649355" "5651901" "5676856" "5797388" "5816472" "5827470" "5931368" "6030472" "6073827").PN. OR ("6354479"). URPN.	US-PGPUB; USPAT; USOCR	OR	OFF	2005/12/01 17:16

L104	18	ceramic.clm. and capillary.clm. and bonding.clm. and (binder or thermoplastic)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/12/01 17:16
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L110	73	"5217154"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/12/01 17:16
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L112	113	65/111.ccls. and color	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/12/01 17:16
L113	165	photolithography and blanks and cutting	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/12/01 17:16
L114	1	10/082867	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/12/01 17:16